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**Zuken News**

**Ref:** **Z0603**

**FOR IMMEDIATE RELEASE:** March 24, 2025

**Zuken Joins IBM Research AI Hardware Center to Develop Next-Generation AI Hardware Solutions**

*Zuken has also signed a joint development agreement with IBM focusing on 3-D integrated circuit packaging, AI hardware acceleration, and EDA workflow advancements*

**YOKOHAMA, JAPAN, March 24, 2025** – Today, Zuken Inc. announced an agreement with IBM to join the IBM Research AI Hardware Center as a commercial member. The IBM Research AI Hardware Center, a global research hub headquartered at the Albany NanoTech Complex in Albany, NY, aims to develop next-generation chips and systems, including advanced semiconductor packaging, that support the processing power and unprecedented speed that AI requires.

Zuken has also signed an agreement with IBM for the joint research and development of heterogeneous chip integration packaging solutions, which is critical for AI accelerator architecture. The collaboration will focus on 3-D integrated circuit (3DIC) packaging design for advanced semiconductors and optimizing Electronic Design Automation (EDA) workflows. Zuken will support the evaluation of a prototype deep learning accelerator core from IBM’s digital and analog projects. Additionally, Zuken will contribute to material development and processes modeling, and integration assembly methods for interconnecting multiple IC dies within a semiconductor packaging module. The agreement will further focus on reliability testing, performance simulation, and hardware validation.

"Zuken is pleased to collaborate with IBM Research as a member of the AI Hardware Center and joint development partner," said Kazuhiro Kariya, Zuken's Senior Managing Executive Officer and CTO. "Our unique system-level design platform supports innovation in 3DIC heterogeneous integration design process by enabling a practical SOC/package/PCB co-design environment. Zuken aims to play an important role in the next-generation high-end device development ecosystem."

“We are thrilled to be working with Zuken to accelerate chip packaging and AI hardware innovation,” said Jeff Burns, Director of the IBM Research AI Hardware Center. “These advances will play a critical role in unlocking the performance and efficiency needed for the future of AI.”

Zuken views 3DIC packaging design as a key enabler for future technological innovation and continues to invest in R&D. Open collaboration with industry consortiums is critical, and our collaboration with IBM Research reflects our commitment to expanding technological capabilities and providing innovative solutions to our customers.

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About Zuken

Zuken is a global software company providing industry leading electrical and electronic design solutions. Founded in 1976, Zuken has a long track record of technology innovation and financial stability in the electronic design automation (EDA) industry. With a product portfolio of world-class design solutions spanning MBSE-based product definition and services to electrical and electronic design solutions to address the needs of a broad range of industries across the globe. These design solutions provide our customers with improved productivity and efficiencies in this highly competitive landscape. For more information about the company and its products, visit [www.zuken.com](http://www.zuken.com).

Press Kit

Text and images are available for download.

Images and captions

**Image 1:** Z0603-1 IBM Research AI Hardware Center

**Caption:** IBM Research AI Hardware Center

**A group of people in a factory

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**Image 2:** Z0603-2 Kariya

**Caption:** Kazuhiro Kariya, Chief Technology Officer, Zuken

**A person in a suit and tie

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**Image 3:** Z0603-3 Jeff Burns

**Caption:** Jeff Burns, Director, IBM Research AI Hardware Center

**A person in a suit

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**For more information, contact your local PR representative:**

**Japan**

Mamoru Hirayama

Zuken, Inc.

2-25-1, Egata-higashi, Tsuzuki-ku

Yokohama 224-8585

Japan

[mamoru.hirayama@jp.zuken.com](mailto:mamoru.hirayama@jp.zuken.com)

Tel: +45-942-1511

**Americas**

**Amy Clements**

Zuken USA, Inc.

238 Littleton RD, STE 100

Westford, MA 01886

United States

[amy.clements@zukenusa.com](mailto:amy.clements@zukenusa.com)

Tel: +1 972-691-3284

**Europe**

**Klaus Wiedemann**

Zuken GmbH

Am Söldnermoos 17

Hallbergmoos 85399

Germany

[klaus.wiedemann@de.zuken.com](mailto:klaus.wiedemann@de.zuken.com)

Tel:+49-89-7104059-58